

ABSTRACT OF THE DISCLOSURE

POLISHING APPARATUS

5 A polishing apparatus capable of increasing an added value is disclosed. The polishing apparatus includes a polishing table configured to support a polishing pad, a top ring configured to press a substrate against the polishing pad, and a liquid supply mechanism configured to supply a liquid onto the polishing pad. The liquid supply mechanism includes a nozzle arm configured to be movable in a radial direction of the
10 polishing table, and a liquid ejection nozzle attached to the nozzle arm. The liquid ejection nozzle is a fan-shaped nozzle having a liquid throttle surface having a tapered shape.

FIG. 1